

AMENDMENTS TO THE CLAIMS

The following is a complete, marked-up listing of revised claims with a status identifier in parenthesis, underlined text indicating insertions, and strike through and/or double-bracketed text indicating deletions.

LISTING OF CLAIMS

1.-21. (Cancelled).

22. (Currently Amended) A capacitor of a semiconductor device, the capacitor comprising:

an interlayer dielectric (ILD) film on a semiconductor substrate, the ILD film including a conductive plug therein;

a lower electrode formed on the ILD film~~a semiconductor substrate~~;

an AHO $((\text{Al}_x, \text{Hf}_{1-x})\text{O}_y)$ film formed on the lower electrode;

an upper electrode formed on the AHO $((\text{Al}_x, \text{Hf}_{1-x})\text{O}_y)$ film; and

an oxidation barrier film formed between the lower electrode and the AHO $((\text{Al}_x, \text{Hf}_{1-x})\text{O}_y)$ film;

a dielectric film having a dielectric constant that is higher than that of the AHO $((\text{Al}_x, \text{Hf}_{1-x})\text{O}_y)$ film between the upper electrode and the AHO $((\text{Al}_x, \text{Hf}_{1-x})\text{O}_y)$ film,

wherein the dielectric film is an HfO_2 layer, a ZrO_2 layer, or an STO layer, ~~and~~

wherein the dielectric film is directly in contact with the upper electrode, and

wherein the lower electrode, the oxidation barrier film and the AHO film include a recess above the conductive plug, and the recess is filled by the upper electrode.

23.-37. (Cancelled).